

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

LT1761IS5-x.x#TRPBF-MS

产品手册

概述

LT1761IS5-x.x#TRPBF-MS 系列是一组低压差 (LDO)转换器, 具有 2.8V 至 20V 宽电压输入范围、低压差、低功耗和小型化封装的等特性, 输出电压范围为 3.0-5.0V。

LT1761IS5-x.x#TRPBF-MS 低至 1.8uA 低静态电流特性,电路也带有 CE 使能控制端口, 可使电路进入休眠状态。特别适合用于电池供 电、长时间待机系统设备应用, 能帮助降低系统设备的待机功耗, 有效延长 待机时间和电池使用寿命。

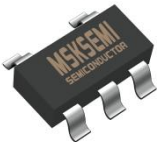
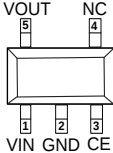
主要特点

- 输入输出电压差低
- 温度漂移系数小
- 耐压 20V
- 工作静态电流 1.8μA, 最大 4μA
- 休眠静态电流最大 0.2μA
- 输出电压精度: ±2%
- 输出过载保护
- 带有 CE 使能控制端口
- 工作温度 - 20°C ~ + 85°C

典型应用

- 手持式、电池供电设备
- 通信设备
- 音频、视频设备
- 低功耗微处理器
- 笔记本电脑、掌上型电脑和 PDA
- 车载导航系统
- 工业控制
- 智能家居

封装脚位信息

SOT-23-5	封装脚位图
	

引脚功能描述

序号	符号	功能描述
1	VIN	输入端
2	VSS	地端
3	CE	使能端
4	NC	悬空
5	VOUT	输出端

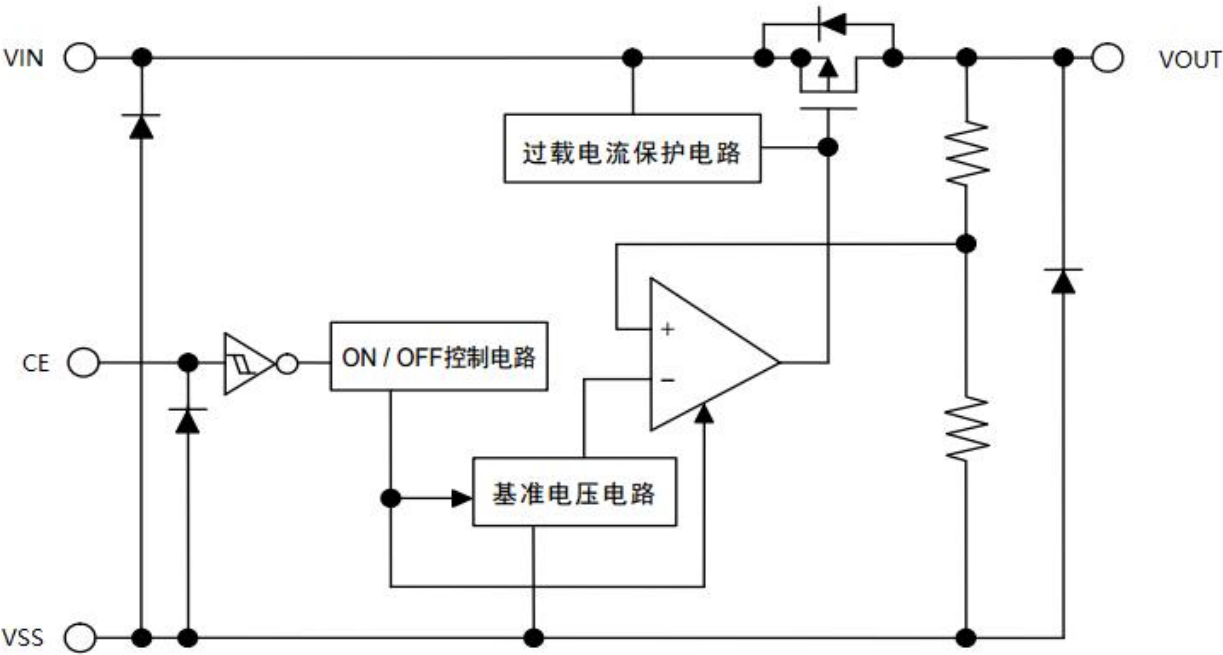
管体标记

LT1761IS5-3.0#TRPBF-MS	LT1761IS5-3.3#TRPBF-MS	LT1761IS5-3.6#TRPBF-MS
		
LT1761IS5-4.0#TRPBF-MS	LT1761IS5-4.4#TRPBF-MS	LT1761IS5-5.0#TRPBF-MS
		

订货信息

型号	输出电压	容差	封装类型	最小包装
LT1761IS5-3.0#TRPBF-MS	3.0V	2%	SOT-23-5	3000PCS
LT1761IS5-3.3#TRPBF-MS	3.3V			
LT1761IS5-3.6#TRPBF-MS	3.6V			
LT1761IS5-4.0#TRPBF-MS	4.0V			
LT1761IS5-4.4#TRPBF-MS	4.4V			
LT1761IS5-5.0#TRPBF-MS	5.0V			

电路方框图



最大额定值 (无特别说明情况下, TA=25°C)

参数说明	符号	数值范围	单位
输入极限电压	V_{IN}	-0.3 ~ +26	V
使能口极限电压	V_{CE}	-0.3 ~ +26	V
输出极限电流	I_{out}	600	mA
贮存温度	T_{STG}	-50 ~ +125	°C
工作温度	T_A	-20 ~ +85	°C
结温 ⁽¹⁾	T_J	150	°C

注：超最大额定值应用可能会对器件造成永久性损伤。

散热信息

参数说明	符号	数值范围	单位
功耗	P_D	200	mW

电气参数 (无特别说明情况下, $T_A=25^{\circ}\text{C}$, $C_{IN}=C_{OUT}=1\mu\text{F}$)

参数说明	符号	测试条件	最小值	典型值	最大值	单位
输入电压	V_{IN}		3.0		20	V
输出电压	V_{OUT}		3.0		5.0	V
输出电压精度		$I_{OUT}=1\text{mA}$	-2		+2	%
输出电流	I_{OUT}	$V_{IN}=V_{OUT}+2.0\text{V}$	—	350	—	mA
负载调整率	ΔV_{OUT}	$V_{IN}=V_{OUT}+2.0\text{V}$ $1\text{mA}\leq I_{OUT}\leq 150\text{mA}$	—	15	—	mV
线性调整率	$\frac{\Delta V_{OUT}}{V_{OUT}} \cdot \Delta V_{IN}$	$V_{OUT}+1.0\text{V}\leq V_{IN}\leq 20\text{V}$ $I_{OUT}=10\text{mA}$	—	0.015	0.2	%/V
低压差	$V_{DIF}^{\textcircled{1}}$	$I_{OUT}=100\text{mA}, V_{OUT}=3.3\text{V}$	—	200	—	mV
静态电流	I_{SS}	$V_{CE}=V_{IN}$	—	1.8	4	μA
休眠电流	$I_{STANDBY}$	$V_{CE}=V_{SS}$			0.2	μA
使能高电平	V_{CEH}	$V_{IN}=V_{OUT}+2.0\text{V}$	1.7		20	V
使能低电平	V_{CEL}	$V_{IN}=V_{OUT}+2.0\text{V}$	0		0.3	V
短路电流	I_{SHORT}	$V_{IN}=V_{OUT}+2.0\text{V}$	—	400	—	mA
温度系数	$\frac{\Delta V_{OUT}}{\Delta T_A} \cdot V_{OUT}$	$V_{IN}=V_{OUT}+2.0\text{V}$ $I_{OUT}=10\text{mA}$ $-40^{\circ}\text{C}\leq T_A\leq 125^{\circ}\text{C}$	—	± 100	—	ppm/ $^{\circ}\text{C}$
输出有源放电电阻	$R_{DIS}^{\textcircled{2}}$	$V_{CE}<0.5\text{V}$		300		Ω

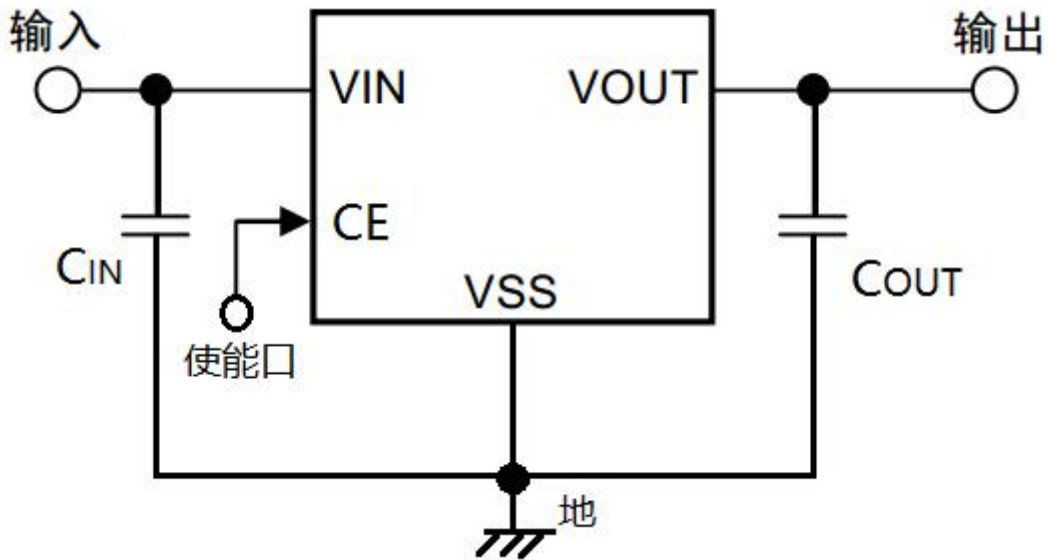
注:

- 1.当 $V_{IN}=V_{OUT}+2.0\text{V}$, 固定负载条件下使输出电压下降2%, 此时输入电压和输出电压的差值为低压 差值 V_{DIF} 。
- 2.输出有源放电电阻 R_{DIS} , 随着 V_{IN} 电压增大而降低。

应用说明

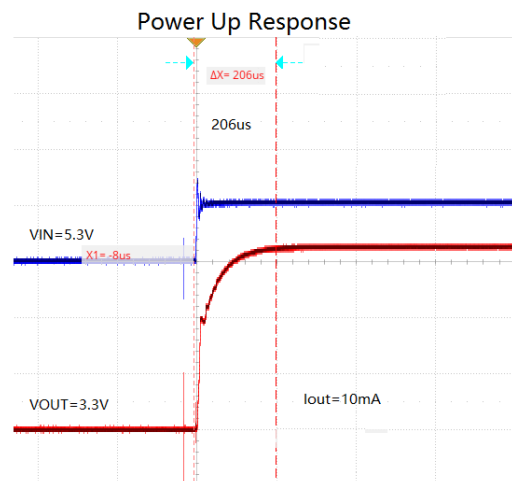
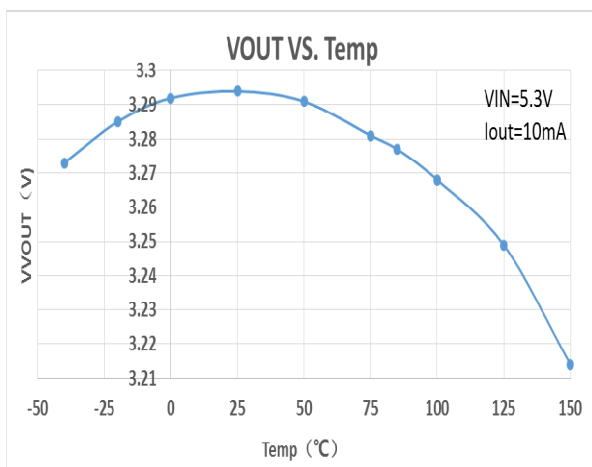
- 1、应用时尽量将电容接到VIN 和VOUT 脚位附近。
- 2、电路内部使用了相位补偿电路和利用输出电容的ESR 来补偿。所以输出到地一定要接大于或者 等于 $1\mu\text{F}$ 的电容器。
- 3、注意输入输出电压、负载电流的使用条件，避免IC 内部的功耗超出封装允许的最大功耗值 。

应用电路



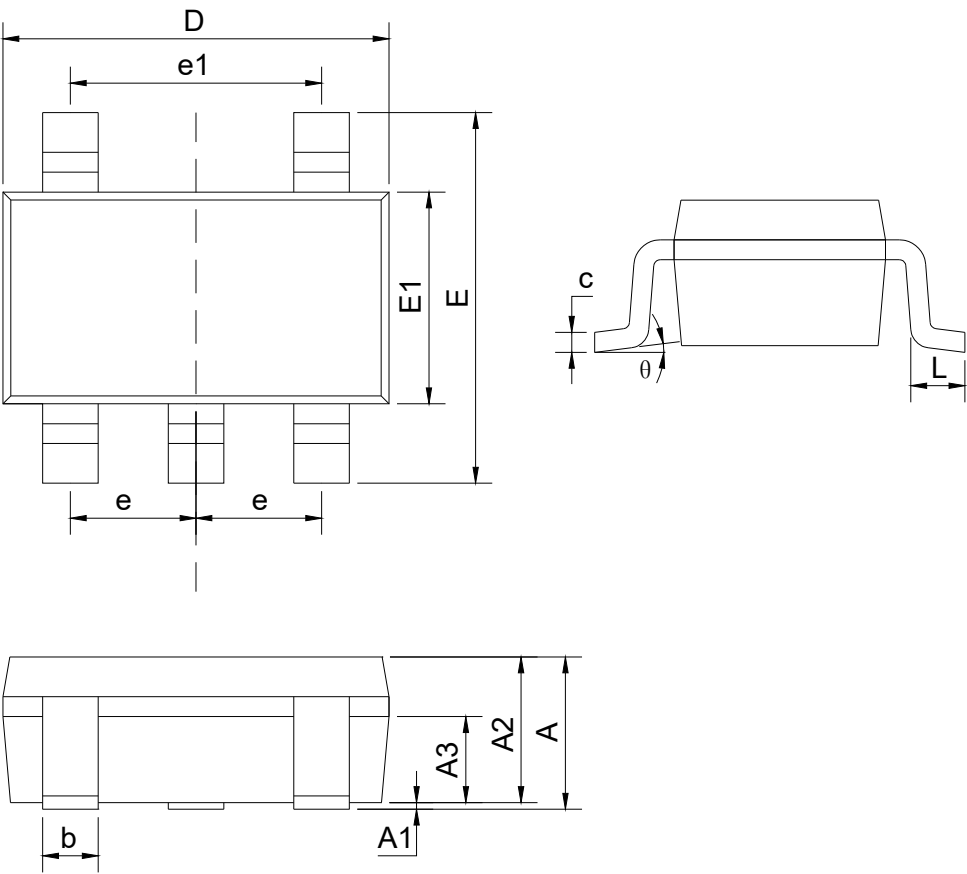
1. C_{IN} 用于稳定输入电容
2. C_{OUT} 可以使用的大于或等于 $1\mu\text{F}$ 的陶瓷电容

典型的性能曲线



封装外形图和尺寸

SOT-23-5



SYMBOL	mm	
	min	max
A		1.35
A1	0.04	0.15
A2	1.00	1.20
A3	0.55	0.75
b	0.38	0.48
c	0.10	0.25
D	2.72	3.12
E	2.60	3.00
E1	1.40	1.80
e	0.95BSC	
e1	1.90BSC	
L	0.30	0.60
θ	0	8°

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